

600V N-Channel MOSFET

Description

The MSF4N60L is a N-channel enhancement-mode MOSFET , providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The TO-220F package is universally preferred for all commercial-industrial applications

Features

- Low On Resistance
- · Simple Drive Requirement
- Low Gate Charge
- Fast Switching Characteristic
- RoHS compliant package

Application (500V-600V)

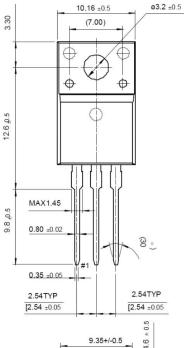
- Open Framed Power Supply
- · Adapter
- STB

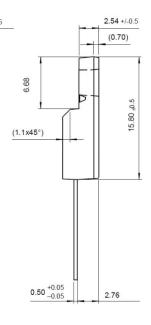
Packing & Order Information

50/Tube ; 1,000/Box



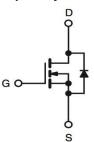








Graphic symbol



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings					
Symbol	Parameter	Value	Unit		
V _{DSS}	Drain-Source Voltage	600	V		
V _{GS}	Gate-Source Voltage	±30	V		
I _D	Drain Current -Continuous (TC=25°C)	4.5	A		
	Drain Current -Continuous (TC=100°C)	2.6	А		
I _{DM}	Drain Current Pulsed	18	A		
I _{AR}	Avalanche Current	4.0	A		
E _{AS}	Single Pulsed Avalanche Energy	48	mJ		
E _{AR}	Repetitive Avalanche Energy	3.1	mJ		
dv/dt	Peak Diode Recovery dv/dt	4.5	V/ns		



600V N-Channel MOSFET

Absolute Maximum Ratings						
Symbol	I Parameter Value					
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C			
TPKG	Maximum Temperature for Soldering @ Package Body for 10 seconds	260	°C			
P _D	Total Power Dissipation (TC = 25 °C)	31	W			
	Derating Factor above 25 °C	0.25	W/°C			
T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C			
TJ	Storage Temperature	150	°C			

Notes;

1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. I_{AS} =4A, V_{DD} =50V, L=7mH, V_{G} =10V, Starting T_J=25°C

3. I_{SD} \leq 4A, di/dt \leq 200A/µs,V_{DD} \leq BV_{DSS}, Starting T_J=25°C

Thermal Characteristics (Tc=25°C unless otherwise noted)					
Symbol	Parameter	Max.	Units		
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction-to-Case	2.6	°C/W		
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction-to-Ambient	62.5	C/VV		

Static Characteristics						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 V$, $I_D = 250 \mu A$	600			V
ΔBV_{DSS}	Breakdown Voltage	$I_{D} = 250 \mu A$, Referenced to 25°C		0.6		V/°C
$/\Delta T_J$	Temperature Coefficient	$I_D = 250 \mu A$, Referenced to 25 C		0.0		V/ C
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.0		4.0	V
	Zero Gate Voltage Drain	$V_{DS} = 600 \text{ V}$, $V_{GS} = 0 \text{ V}$			1	μA
I _{DSS}	Current	$V_{DS} = 480 \text{ V}$, $T_{C} = 125^{\circ}\text{C}$			10	
	Gate-Body Leakage	$V_{GS} = \pm 30$			±100	nA
I _{GSS}	Forward	VGS00			100	
R _{DS(ON)}	Static Drain-Source	$V_{GS} = 10 \text{ V}, I_{D} = 3.5 \text{ A}$		0.9	1.4	Ω
	On-Resistance			0.3	1.7	52

Dynamic Characteristics							
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units	
C _{ISS}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0MHz		1482		pF	
C _{OSS}	Output Capacitance			121.7		pF	
C _{RSS}	Reverse Transfer Capacitance			14		pF	



600V N-Channel MOSFET

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
t _{d(on)}	Turn-On Time	V_{DS} = 300 V, I_{D} = 7 A, R_{G} = 25 Ω , V_{GS} = 10 V		10	30	ns
t _r	Turn-On Time			40	80	ns
t _{d(off)}	Turn-Off Delay Time			40	100	ns
tf	Turn-Off Fall Time			50	90	ns
Qg	Total Gate Charge	$V_{DS} = 300 \text{ V}, I_D = 7 \text{ A},$ $V_{GS} = 10 \text{ V}$		28	37	nC
Q _{gs}	Gate-Source Charge			4.7		nC
Q _{gd}	Gate-Drain Charge			11		nC

Source-Drain Diode						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
I _S		$V_D = V_G = 0$			4.0	•
I _{SM}		V _S = 1.3 V			16	A
V _{SD}		$I_{S} = 4 \text{ A}$, $V_{GS} = 0 \text{ V}$		0.85	1.0	V
t _{rr}		$I_F = 7 \text{ A}$, $V_{GS} = 0 \text{ V}$		350		ns
Q _{rr}		diF/dt=100A/µs		3.3		μC

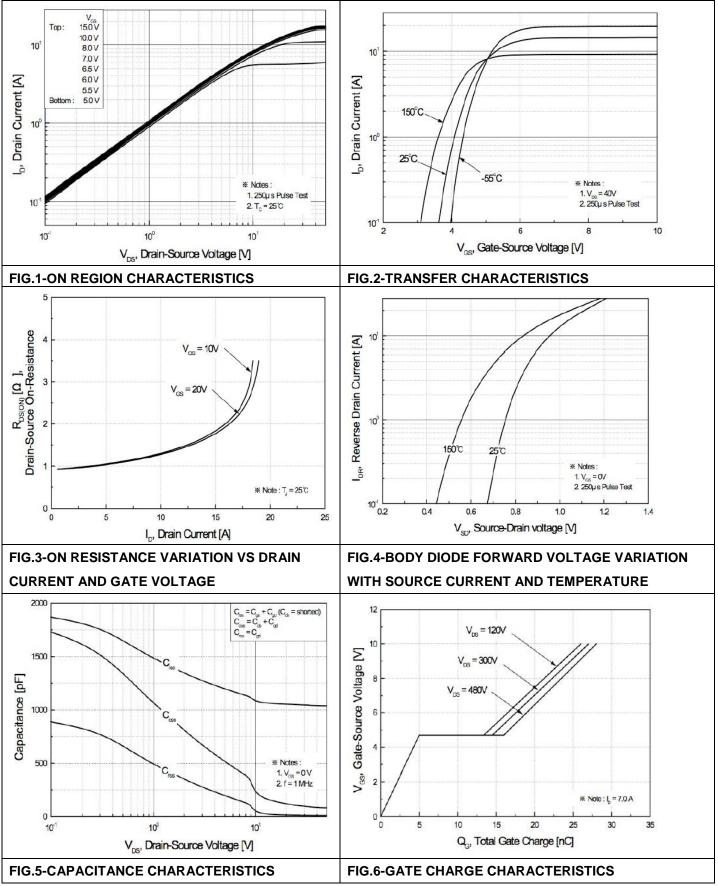
Notes;

1. Pulse Test: Pulse Width ≦ 300µs, Duty Cycle≦ 2%



600V N-Channel MOSFET

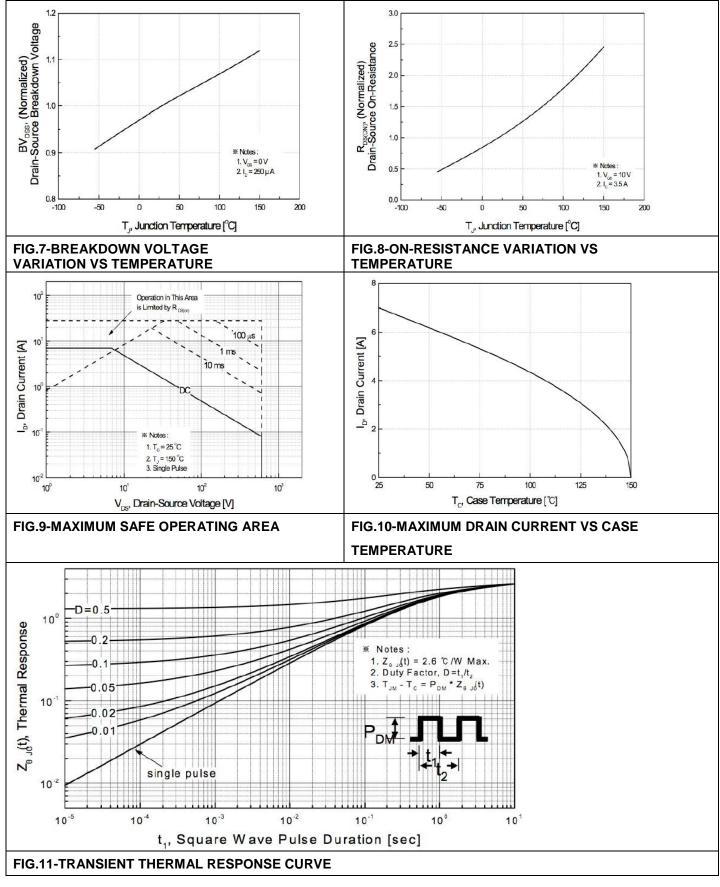
Characteristics Curve





600V N-Channel MOSFET

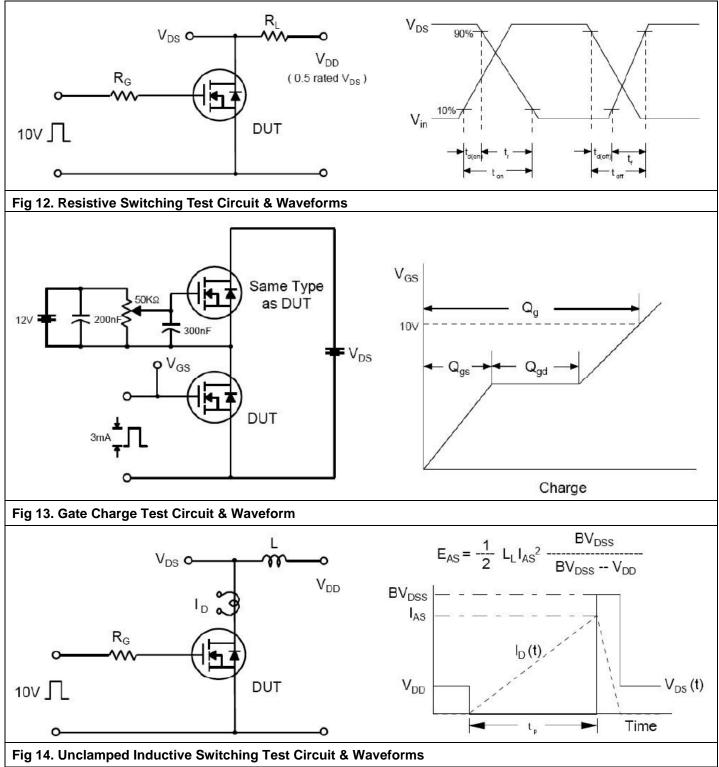
Characteristics Curve





600V N-Channel MOSFET

Characteristics Test Circuit & Waveform





600V N-Channel MOSFET

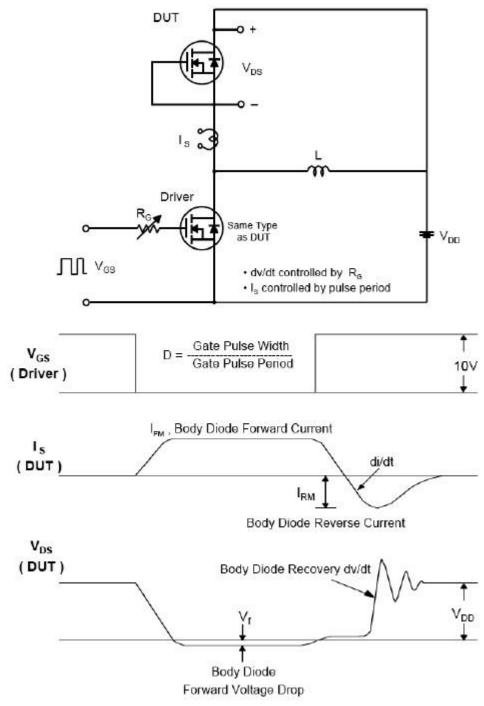


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



600V N-Channel MOSFET

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE. Bruckewell Technology Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Bruckewell"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product. Bruckewell makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Bruckewell disclaims

- (i) Any and all liability arising out of the application or use of any product.
- (ii) Any and all liability, including without limitation special, consequential or incidental damages.

(iii) Any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Bruckewell's knowledge of typical requirements that are often placed on Bruckewell products in generic applications.

Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time.

Product specifications do not expand or otherwise modify Bruckewell's terms and conditions of purchase, including but not limited to the warranty expressed therein.